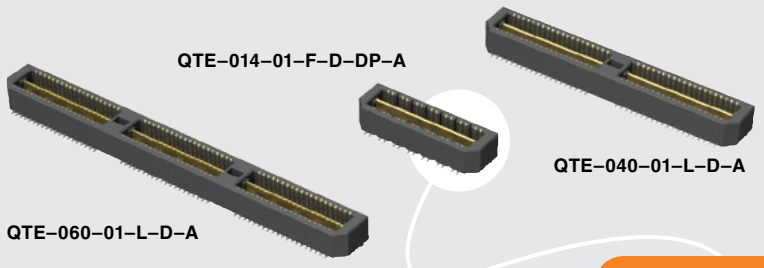
samtec

QSTRIP®

(0.80 mm) .0315"



QTE SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTE

Insulator Material: Liquid Crystal Polymer
Terminal Material: Phosphor Bronze
Plating: Au or Sn over 50 µ" (1.27 µm) Ni
Current Rating: Contact: 2 A per pin (2 pins powered) Ground Plane: 23 A per ground plane (1 ground plane powered)
Operating Temp Range: -55 °C to +125 °C
Voltage Rating: 225 VAC mated with QSE & 5 mm Stack Height
Max Cycles: 100
RoHS Compliant: Yes

PROCESSING

Lead–Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (020-060)
Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

FILE NO: 090871_0_000

PROTOCOLS

- 100 GbE
- XAUI
- PCI Express®
- SATA
- MGT (Rocket I/O)
- InfiniBand™

ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 µ" (0.76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount, Guide Posts, Screw Down & Friction Lock
- 56 (-DP), 80, 100 positions per row
- Retention Option

Contact Samtec.

Board Mates: QSE

Cable Mates: EQCD, EQDP (See Also Available Note)

Standoffs: SO

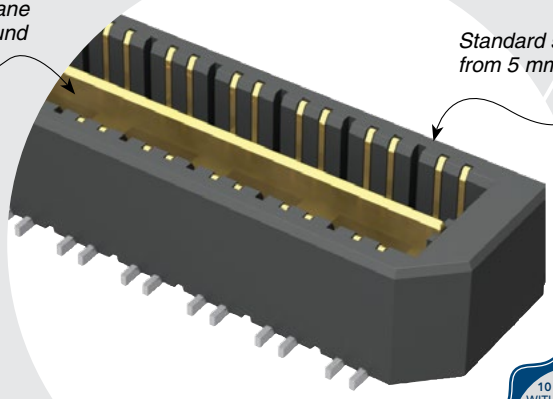
POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

Integral metal plane for power or ground

Standard stack heights from 5 mm to 25 mm



10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

HIGH-SPEED CHANNEL PERFORMANCE		
QTE-D/QSE-D or QTE-DP/QSE-DP @ 5 mm Mated Stack Height *Rating based on Samtec reference channel.For full SI performance data visit Samtec.comor contact SIG@samtec.com*	QTE-D/QSE-D	QTE-DP/QSF-DP
	14 Gbps	28 Gbps

QTE	–	PINS PER ROW NO. OF PAIRS	–	LEAD STYLE	–	PLATING OPTION	–	TYPE	–	A	–	OTHER OPTION

PINS PER ROW NO. OF PAIRS

–020, –040, –060
(40 total pins per bank = –D)

–014, –028, –042
(14 pairs per bank = –D–DP)

LEAD STYLE

Specify LEAD STYLE from chart

PLATING OPTION

–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

–L
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150µ" (3.81 µm) Ni on Signal Pins in contact area, 10 µ" (0.25 µm) min Au over 50 µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1.27 µm) min Ni on all solder tails

TYPE

–D
= Single-Ended

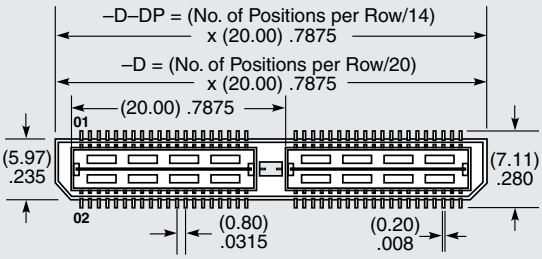
–D–DP
= Differential Pair (–01 only)

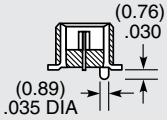
OTHER OPTION

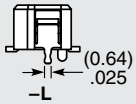
–K
= (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

–TR
= Tape & Reel Packaging (N/A –05 & –07 lead style)

–L
= Latching Option (N/A on –042 & –060 positions)







***Note:** –C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

QTE LEAD STYLE	A	HEIGHT WITH QSE*
–01	(4.27) .168	(5.00) .197
–02	(7.26) .286	(8.00) .315
–03	(10.27) .404	(11.00) .433
–04	(15.25) .600	(16.00) .630
–05	(18.26) .718	(19.00) .748
–07	(24.24) .954	(25.00) .984
–09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.